

**AMENDMENT TRANSMITTAL LETTER (Large Entity)**

Applicant(s): Tien-Jen Cheng, et al.

Docket No.

FIS920030103US1

Application No. 10/604,578	Filing Date 07/31/2003	Examiner Nathan W. Ha	Customer No. 32,074	Group Art Unit 2814	Confirmation No. 1577
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Invention: **ENCAPSULATED PIN STRUCTURE FOR IMPROVED RELIABILITY OF WAFER****COMMISSIONER FOR PATENTS:**

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

**CLAIMS AS AMENDED**

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	15 -	20 =	0	x \$50.00	\$0.00
INDEP. CLAIMS	2 -	3 =	0	x \$200.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

No additional fee is required for amendment.

Please charge Deposit Account No. \_\_\_\_\_ in the amount of \_\_\_\_\_

A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.

The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account 09-0458

Any additional filing fees required under 37 C.F.R. 1.16.

Any patent application processing fees under 37 CFR 1.17.

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**WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.**



Signature

Dated: July 19, 2006

Rosa B. Suazo, Esq.  
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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on

(Date)  
EF5

Signature of Person Mailing Correspondence

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CC:

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<b>In re application of:</b> Tien-Jen Cheng, et al.	<b>Dated:</b> July 19, 2006
<b>Serial Number:</b> 10/604,578	<b>Examiner:</b> Nathan W. Ha
<b>Filing date:</b> July 31, 2003	<b>Group Art Unit:</b> 2814
<b>Title:</b> Encapsulated Pin Structure For Improved Reliability Of Wafer	IBM Corporation D/18G, B/321, Zip 482 2070 Route 52 Hopewell Junction, NY 12533-6531

**AMENDMENT UNDER 37 C.F.R. § 1.111**

Hon. Commissioner for Patents and Trademarks  
P.O. Box 1450  
Alexandria VA 22313-1450

Sir:

In response to the Office Action dated April 24, 2006, Applicant respectfully request reconsideration and allowance of the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of Claims beginning on page 3 of this paper.

**Amendments to the Drawings** begin on page 8 of this paper and include an attached replacement sheet and a marked-up copy.

**Remarks** begin on page 9 of this paper.